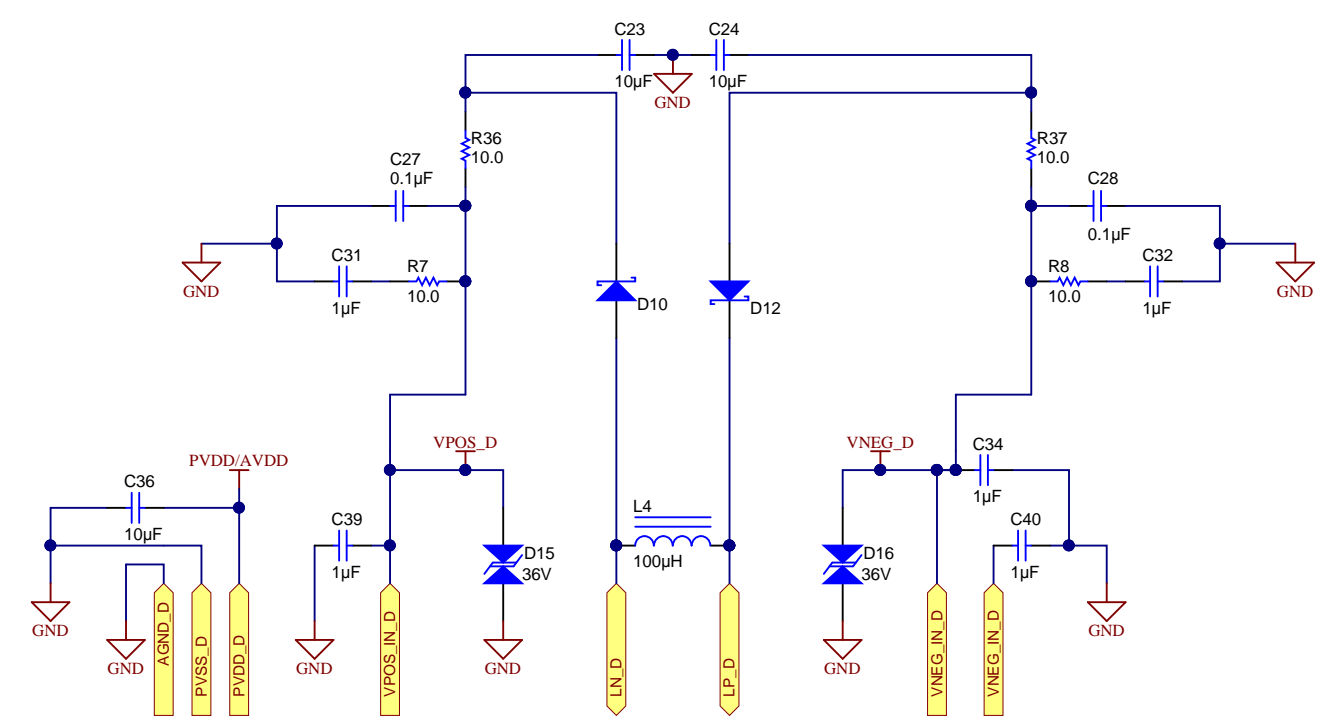
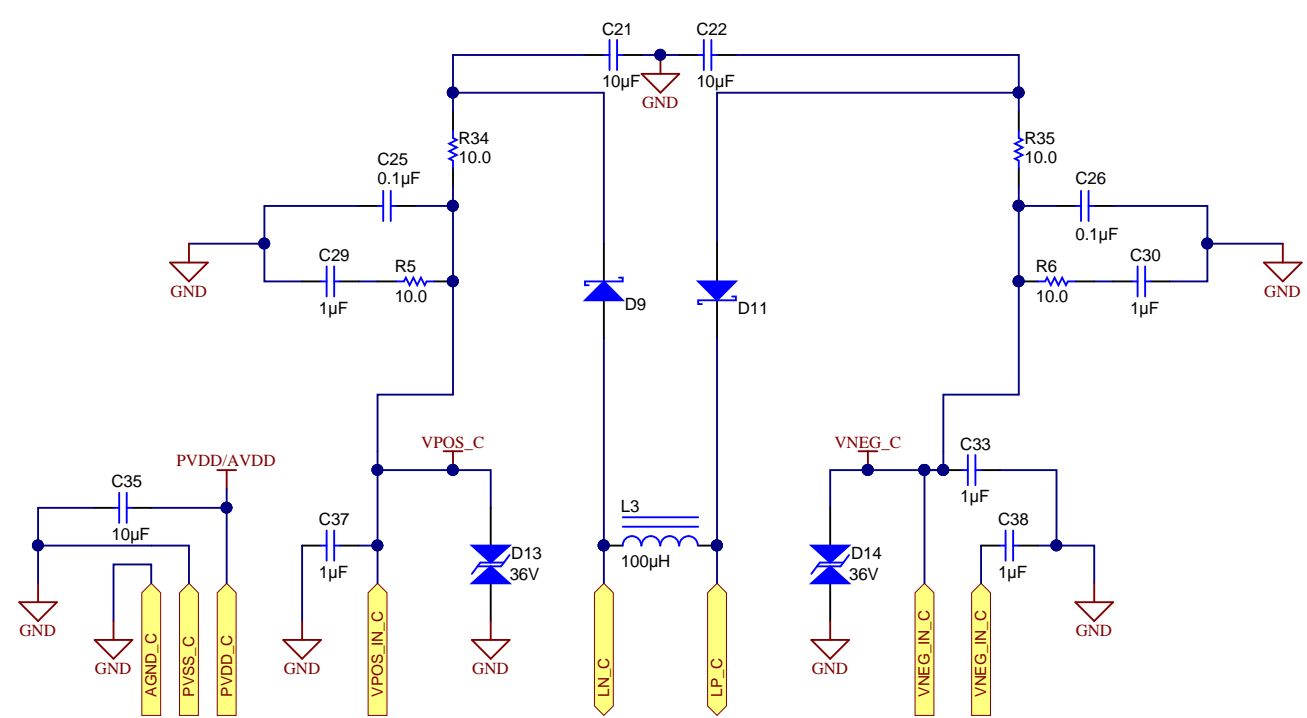
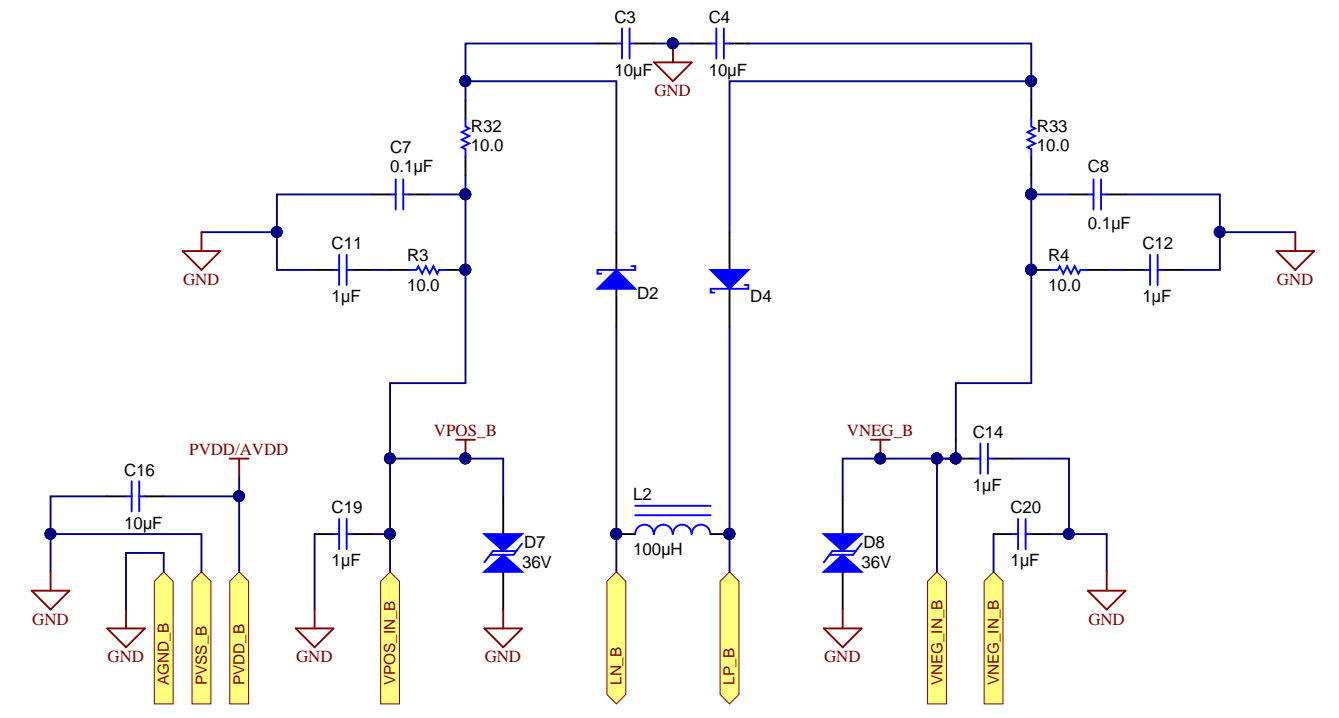
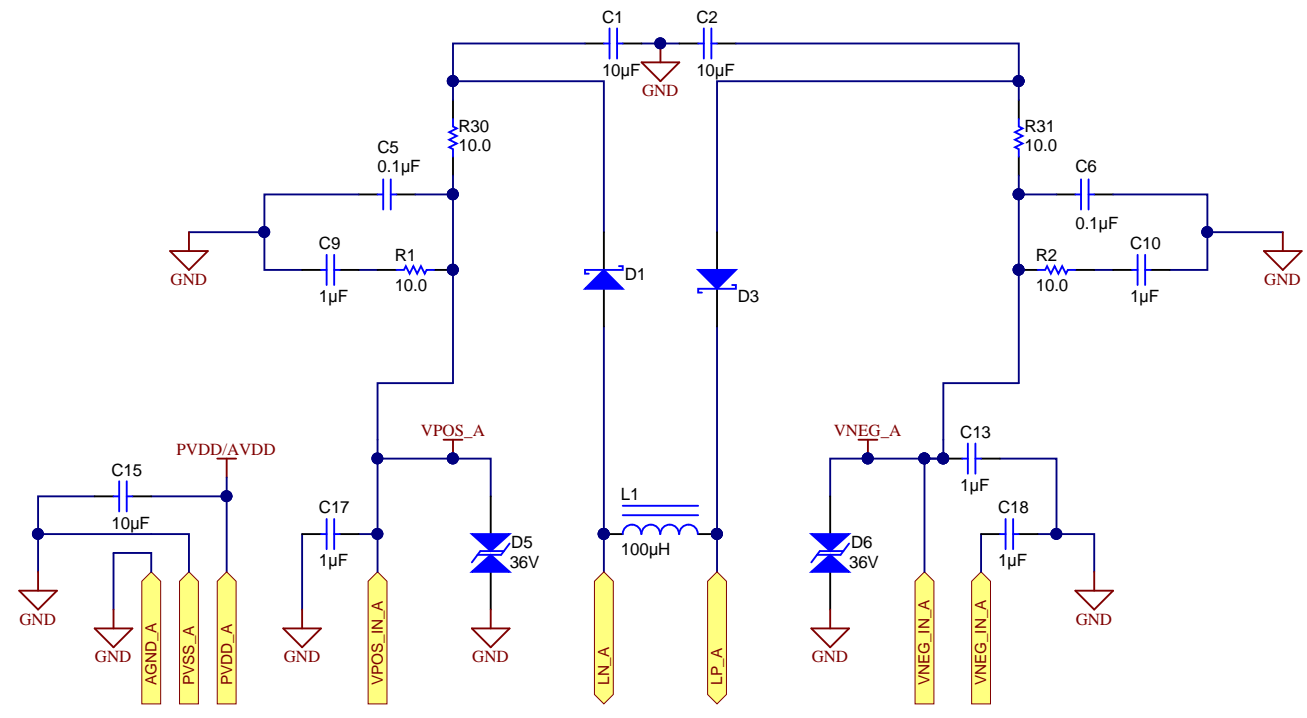


Orderable: N/A	Designed for: Public Release	Mod. Date: 2/16/2017
TID #: TIPD216	Project Title: Quad Channel Analog Output Modul with Adaptive	
Number: TIPD216	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 2 of 3
Drawn By:	File: TIPD216_Device.SchDoc	Size: B
Engineer: Kevin Duke	Contact: http://www.ti.com/support	

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EMI Test



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Orderable: N/A	Designed for: Public Release	Mod. Date: 2/16/2017
TID #: TIPD216	Project Title: Quad Channel Analog Output Module with Adaptive	
Number: TIPD216	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 2 of 3
Drawn By:	File: TIPD216_DAC8775SMPS.SchDoc	Size: B
Engineer: Kevin Duke	Contact: http://www.ti.com/support	



EMI Test

A

A



PCB Number: TIPD216
PCB Rev: E1

PCB
LOGO
Pb-Free Symbol

You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

B

B

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

C

C

D

D

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TID #: TIPD216	Project Title: Quad Channel Analog Output Module with Adaptive		
Number: TIPD216	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 3 of 3	
Drawn By:	File: TIPD216_Hardware.SchDoc	Size: B	
Engineer: Kevin Duke	Contact: http://www.ti.com/support		

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